

L to S BAND LOW NOISE AMPLIFIER N-CHANNEL GaAs MES FET

DESCRIPTION

NEC

NE76118 is a n-channel GaAs MES FET housed in MOLD package.

FEATURES

- Low noise figure NF = 0.8 dB TYP. at f = 2 GHz
- High associated gain Ga = 13.5 dB TYP. at f = 2 GHz
- Gate width : Wg = 400 μ m
- 4 pins super mini mold
- Tape & reel packaging only available

ORDERING INFORMATION

PART NUMBER	QUANTITY	PACKING STYLE
NE76118-T1	3 Kpcs/Reel.	Embossed tape 8 mm wide. Pin 3 (Source), Pin 4 (Drain) face to perforation side of the tape.
NE76118-T2	3 Kpcs/Reel.	Embossed tape 8 mm wide. Pin 1 (Source), Pin 2 (Gate) face to perforation side of the tape.



ABSOLUTE MAXIMUM RATINGS (TA = 25 °C)

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Drain to Source Voltage	Vds	5.0	V
Gate to Source Voltage	Vgso	-5.0	V
Gate to Drain Voltage	Vgdo	-6.0	V
Drain Current	lD	IDSS	mA
Total Power Dissipation	Ptot	130	mW
Channel Temperature	Tch	150	°C
Storage Temperature	Tstg	–65 to +150	°C



RECOMMENDED OPERATING CONDITION (TA = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	Unit
Drain to Source Voltage	Vds		3	4	V
Drain Current	lo		10	20	mA
Input Power	Pin			0	dBm

ELECTRICAL CHARACTERISTICS (TA = 25 °C)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS		
Gate to Source Leak Current	lgso	_	-	10	μA	Vgs = -5 V		
Saturated Drain Current	ldss	30	-	100	mA	$V_{DS} = 3 V, V_{GS} = 0 V$	/	
Gate to Source Cut off Voltage	VGS(off)	-0.5	-	-3.0	V	V _{DS} = 3 V, I _D = 100 μA		
Transconductance	gm	20	45	-	mS	V _{DS} = 3 V, I _D = 10 mA		
Noise Figure	NF		0.8		dB	f = 2 GHz	Vds = 3 V	
Associated Gain	Ga		13.5		dB		I⊳ = 10 mA,	
Noise Figure	NF		0.9	1.4	dB	f = 4 GHz		
Associated Gain	Ga	9.5	10.5		dB			

loss rank is specified as follows.

 $K\ :\ 30\ to\ 100\ mA$

M : 50 to 100 mA $\,$



TYPICAL CHARACTERISTICS (TA = 25 °C)

S-PARAMETER

 $V_{DS} = 3 V$, $I_{D} = 10 mA$

FREQUENCY	S	S11	S	21	S	12	S	322	MSG	К
MHz	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.	MAG.	ANG.		
		(deg.)		(deg.)		(deg.)		(deg.)	dB	
500	.992	-12.2	3.647	162.5	.020	83.0	.765	-5.9	22.6	.17
600	.979	-14.7	3.618	158.3	.024	83.3	.759	-7.3	21.8	.23
700	.964	-17.6	3.594	154.7	.027	81.7	.757	-9.1	21.2	.29
800	.943	-20.2	3.536	151.0	.032	80.5	.747	-10.0	20.5	.38
900	.923	-22.6	3.510	148.4	.034	81.6	.739	-11.5	20.1	.41
1000	.911	-24.9	3.492	145.2	.038	78.7	.736	-12.0	19.7	.47
1100	.900	-27.6	3.477	142.4	.043	77.7	.727	-13.8	19.1	.47
1200	.894	-29.8	3.473	139.0	.046	76.9	.734	-14.3	18.8	.49
1300	.885	-32.5	3.453	135.8	.049	76.0	.724	-16.0	18.5	.50
1400	.868	-35.1	3.410	132.2	.054	75.2	.724	-17.3	18.0	.52
1500	.842	-37.1	3.359	129.3	.057	74.0	.712	-18.9	17.7	.58
1600	.817	-39.9	3.325	125.9	.061	72.9	.707	-20.1	17.4	.63
1700	.783	-42.2	3.269	122.8	.064	72.0	.692	-21.0	17.1	.70
1800	.759	-45.0	3.235	119.6	.067	71.1	.689	-22.2	16.8	.73
1900	.734	-47.6	3.197	116.6	.070	70.1	.676	-22.7	16.6	.78
2000	.712	-50.0	3.152	113.3	.074	70.0	.676	-23.9	16.3	.80
2100	.686	-51.5	3.086	110.2	.075	68.7	.663	-25.0	16.1	.87
2200	.680	-52.6	3.026	107.8	.077	68.2	.653	-26.7	15.9	.89
2300	.667	-55.1	3.013	105.2	.081	68.3	.644	-27.7	15.7	.89
2400	.641	-58.1	2.999	102.1	.085	68.2	.640	-29.4	15.5	.89
2500	.612	-61.0	2.978	99.3	.089	67.3	.631	-30.6	15.3	.92
2600	.589	-63.8	2.944	96.3	.092	67.9	.627	-32.0	15.1	.93
2700	.570	-66.5	2.904	93.5	.095	67.0	.623	-32.9	14.9	.95
2800	.556	-68.9	2.862	90.7	.099	66.9	.620	-34.1	14.6	.95
2900	.540	-70.5	2.809	88.0	.102	66.4	.614	-35.1	14.4	.97
3000	.520	-72.6	2.768	85.3	.107	66.8	.602	-36.3	14.1	.98

S-Parameter

 V_{DS} = 3 V, I_D = 10 mA START 100 MHz, STOP 3 GHz, STEP 100 MHz



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RECOMMENDED SOLDERING CONDITIONS

The following conditions (see table below) must be met when soldering this product.

Please consult with our sales offices in case other soldering process is used, or in case soldering is done under different conditions.

<TYPES OF SURFACE MOUNT DEVICE>

For more details, refer to our document "SEMICONDUCTOR DEVICE MOUNTING TECHNOLOGY MANUAL" (C10535E).

Soldering process	Soldering conditions	Symbol
VPS	Package peak temperature : 215 °C, Time : 40 seconds MAX. (200 °C MIN.), Number of times : 2, Number of days : not limited*	VP15-00-2
Wave soldering	Soldering bath temperature: 260 °C MAX., Time: 10 seconds MAX., Number of times: 1, Number of days: not limited*	WS60-00-1
Infrared ray reflow	Peak package's surface temperature: 230 °C or below, Reflow time: 30 seconds or below (210 °C or higher), Number of reflow process: 2, Exposure limit*: None	IR30-00-2
Partial heating method	Terminal temperature: 230 °C or below, Flow time: 10 seconds or below, Exposure limit*: None	

* Exposure limit before soldering after dry-pack package is opened. Storage conditions: 25 °C and relative humidity at 65 % or less.

Note Do not apply more than a single process at once, except for "Partial heating method".

PRECAUTION Avoid high static voltage and electric fields, because this device is MES FET with GaAs shottky barrier gate.

[MEMO]

Caution

The Great Care must be taken in dealing with the devices in this guide. The reason is that the material of the devices is GaAs (Gallium Arsenide), which is designated as harmful substance according to the law concerned. Keep the law concerned and so on, especially in case of removal.

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- Standard: Computers, office equipment, communications equipment, test and measurement equipment, audio and visual equipment, home electronic appliances, machine tools, personal electronic equipment and industrial robots
- Special: Transportation equipment (automobiles, trains, ships, etc.), traffic control systems, anti-disaster systems, anti-crime systems, safety equipment and medical equipment (not specifically designed for life support)
- Specific: Aircrafts, aerospace equipment, submersible repeaters, nuclear reactor control systems, life support systems or medical equipment for life support, etc.

The quality grade of NEC devices is "Standard" unless otherwise specified in NEC's Data Sheets or Data Books. If customers intend to use NEC devices for applications other than those specified for Standard quality grade, they should contact an NEC sales representative in advance.

Anti-radioactive design is not implemented in this product.